


- 보안등급A 문서로 외부반출 금지 하며, 활용시 표준센터 “관리본” 인증을 받아야만 표준문서의 효력이 있음 -

	<h1>Pre-PCN</h1>			Write	Review	Approval
				replaced by BPM		
Draft	SVC CS CT			/	/	/
The change	Chip Bump Material Change					
Applied product	Refer to explanation sheet		Changed Process	LED Chip Bump paste		
4M	Environment (production site)	Method (classification)	Machine (equipment improvement)	Material (New material)		
Reason	LED DUV3030 Package's(CUD7QF1A , CU7GF1A(B)) chip bump and process change (Au → AuSn) for the purpose of quality improvement.					
Applied date	after customer's approval	BOM	<input checked="" type="checkbox"/> Change <input type="checkbox"/> No Change	Effected process	LED Package's Front process(Die Attach)	
Item		AS-IS		TO-BE		
■ Change Point - LED Chip Bump paste		■ As-Is - LED Package's Front process(Flip bonding) - Chip Bump : Au Bump Paste *CUD7QF1A, CUD7GF1A, CUD7GF1B		■ To-Be - LED Package's Front process(Die Attach) - Chip Bump : AuSn Paste CUD7QF1A, CUD7GF1A, CUD7GF1B		
		■ 변경 전 BOM 내역		■ 변경 후 BOM 내역		
		Application of Chip Paste Au		Application of Chip Paste AuSn		
■ Effect -. quality improvement						
Review						
■ Comment (draft team)						
■ Comment (approval team)						
Status	Applied Date	Initial product	Expected date of shipment.		unchanged stock	
	after customer's approval	-	-		-	
Approval (internal)	Approval	No approved	-	PCN	No need	Need
	(waiting)	-		to a customer	-	o
Reception team	team	team	team	write	review	approval
	replaced by BPM			replaced by BPM		
	/	/	/	/	/	/